

# SOT536-1

plastic low profile fine-pitch ball grid array package; 96 balls;  
body 13.5 x 5.5 x 1.05 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA96
<b>Package type industry code</b>	LFBGA96
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	5-2-2003

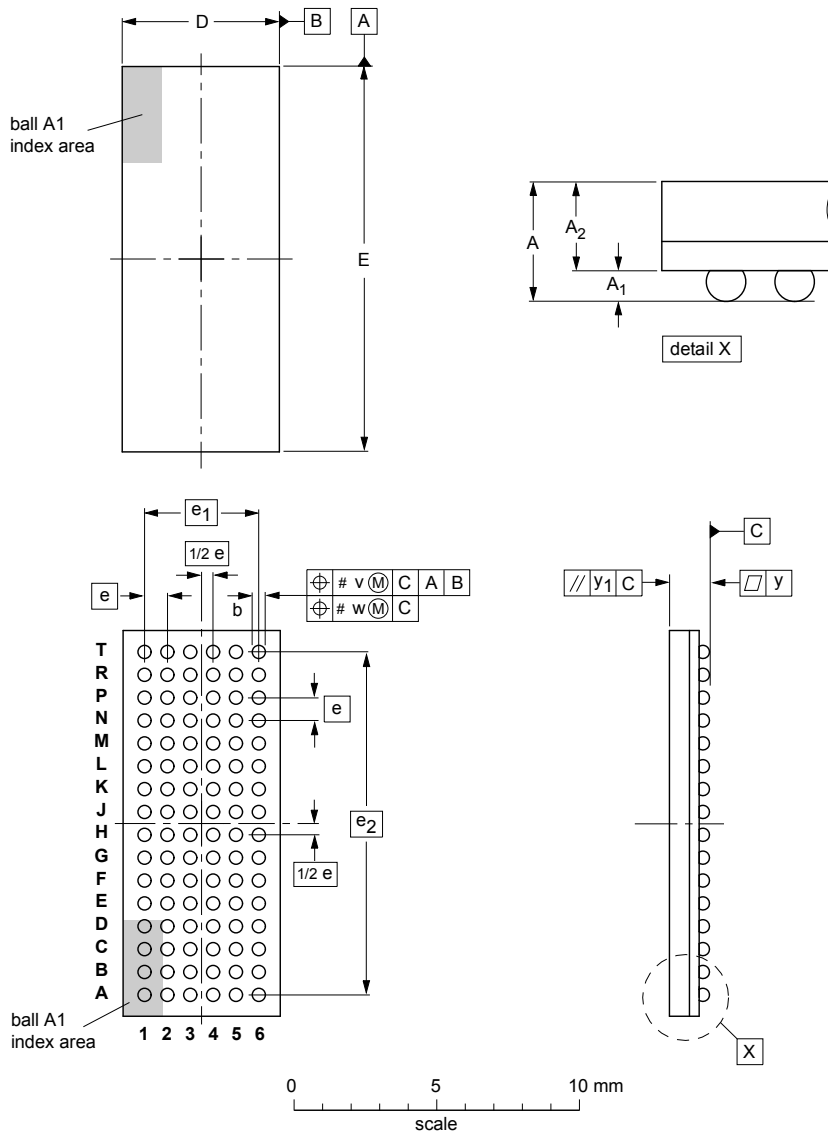
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.4	-	5.5	5.6	mm
E	package width	13.4	-	13.5	13.6	mm
A	seated height	[tbd]	-	1.5	1.5	mm
A <sub>2</sub>	package height	0.9	-	1.05	1.2	mm
n <sub>2</sub>	actual quantity of termination	-	-	96	-	



## 2. Package outline

LFBGA96: plastic low profile fine-pitch ball grid array package; 96 balls; body 13.5 x 5.5 x 1.05 mm SOT536-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1.5	0.41 0.31	1.2 0.9	0.51 0.41	5.6 5.4	13.6 13.4	0.8	4	12	0.15	0.1	0.1	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT536-1						-00-03-04- 03-02-05

Fig. 1. Package outline LFBGA96 (SOT536-1)

### 3. Soldering

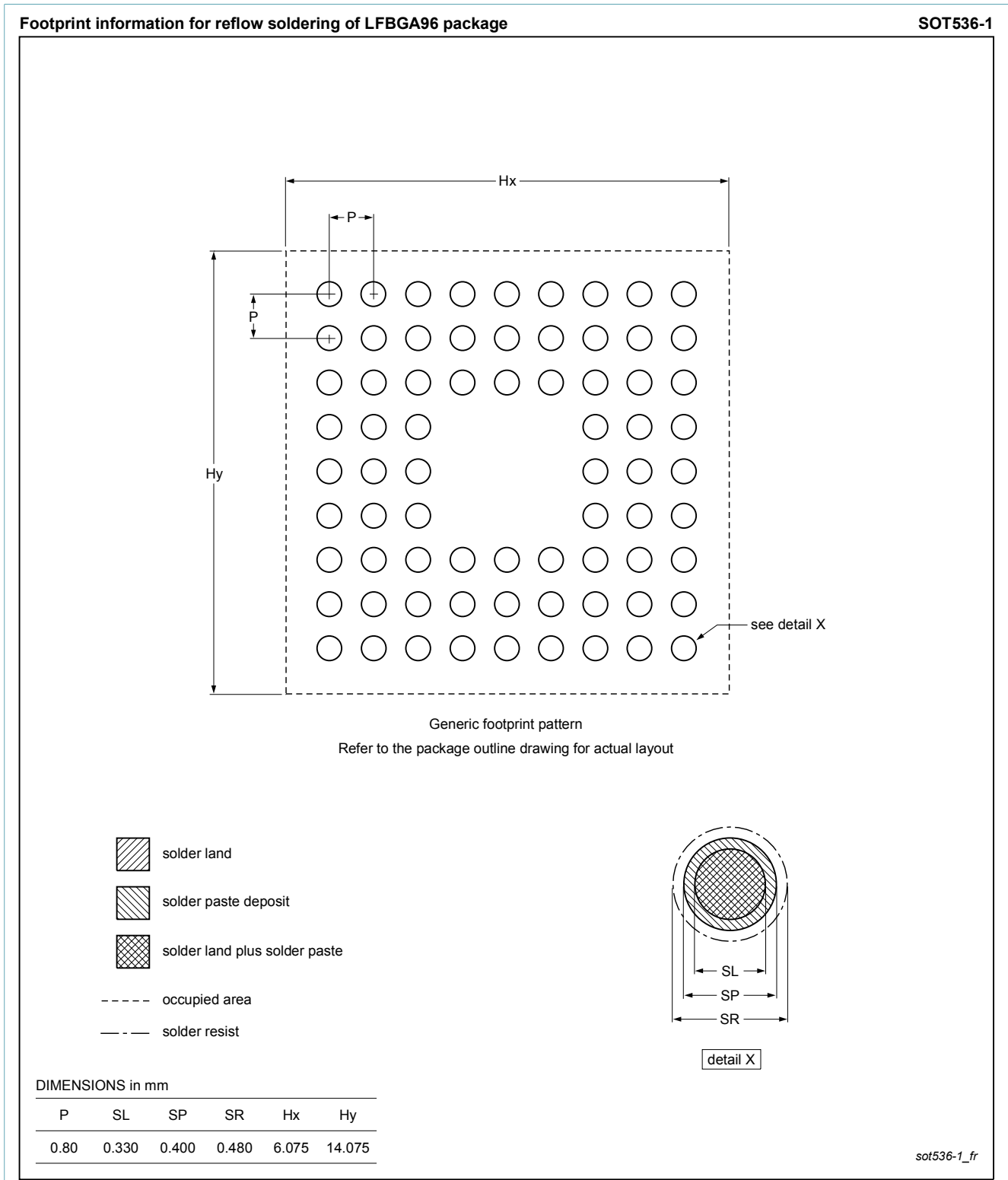


Fig. 2. Reflow soldering footprint for LFBGA96 (SOT536-1)

## 4. Legal information

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